

WHAT IS CLAIMED IS:

1. A semiconductor device comprising:

a flexible printed circuit having a connection terminal portion that includes a plurality of land-shaped connection terminals arranged in a step form or a grid form and an insulating film provided to a wiring connected with the respective land-shaped connection terminals; and

a semiconductor chip mounted on the flexible printed circuit.

2. A semiconductor device according to claim 2, wherein the land-shaped connection terminals are commonly used as terminals for electrical test.

3. A method of manufacturing a semiconductor device, comprising the steps of:

forming a flexible printed circuit including a connection terminal portion in which a plurality of land-shaped connection terminals are arranged in a step form or a grid form and an insulating film is provided to a conductor connected with the respective land-shaped connection terminals;

mounting a semiconductor chip on the flexible printed circuit; and

separating a semiconductor device from the flexible printed circuit by cutting a portion of each of outermost land-shaped

connection terminals of the land-shaped connection terminals arranged in the step form or the grid form in the flexible printed circuit.

4. A method of manufacturing a semiconductor device according to claim 3, further comprising a test step of performing an electrical test using the land-shaped connection terminals.

5. A method of manufacturing a semiconductor device according to claim 4, wherein the semiconductor chip is tested in the test step.

6. A method of manufacturing a semiconductor device according to claim 4, wherein a pattern test of the flexible printed circuit is performed in the test step.

7. An electronic device comprising:

a flexible printed circuit having a connection terminal portion that includes a plurality of connection terminal lands arranged in a step form or a grid form and an insulating film provided to a wiring connected with the respective connection terminal lands;
a semiconductor chip mounted on the flexible printed circuit;
and

an electronic part operated at a time when an output signal

from the semiconductor chip is inputted through the plurality of connection terminal lands.

8. An electronic device according to claim 7, wherein the electronic part comprises a terminal portion provided in a region connected with the flexible printed circuit, and the terminal portion comprises a plurality of terminals provided at positions opposed to the connection terminal lands of the flexible printed circuit and a plurality of wirings which are connected with the terminals and covered with an insulating film.

9. An electronic device according to claim 7, wherein the electronic part is a display panel having a display screen.